

FEATURES:

- Typical  $t_{sk(o)}$  (Output Skew) < 250ps
- ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)
- $V_{cc} = 3.3V \pm 0.3V$ , Normal Range
- $V_{cc} = 2.7V$  to  $3.6V$ , Extended Range
- CMOS power levels (0.4 $\mu$ W typ. static)
- All inputs, outputs, and I/O are 5V tolerant
- Supports hot insertion
- Available in TSSOP package

DRIVE FEATURES:

- High Output Drivers:  $\pm 24mA$
- Reduced system switching noise

APPLICATIONS:

- 5V and 3.3V mixed voltage systems
- Data communication and telecommunication systems

DESCRIPTION:

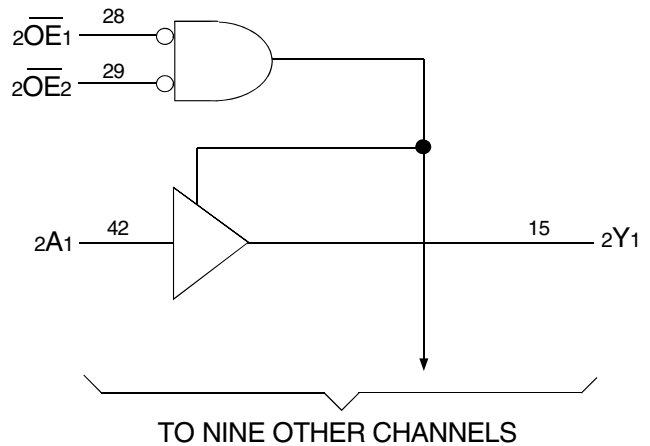
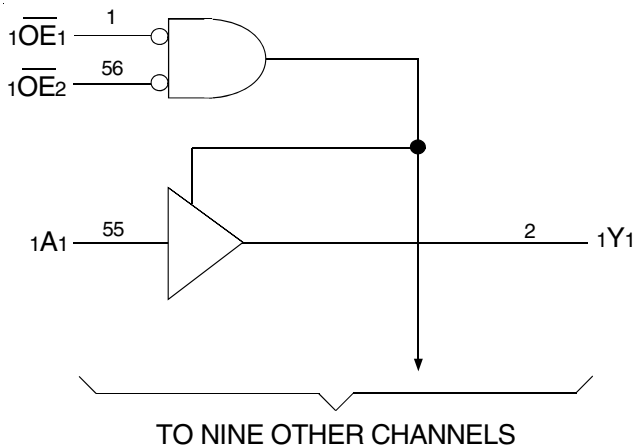
This 20-bit buffer is built using advanced dual metal CMOS technology. The LVC16827A provides high-performance bus interface buffering for wide data/address paths or buses carrying parity. Two pairs of NAND-ed output enable controls offer maximum control flexibility and are organized to operate the device as two 10-bit buffers or one 20-bit buffer. Flow-through organization of signal pins simplifies layout. All inputs are designed with hysteresis for improved noise margin.

The LVC16827A buffer is ideally suited for driving high capacitance loads and low impedance backplanes.

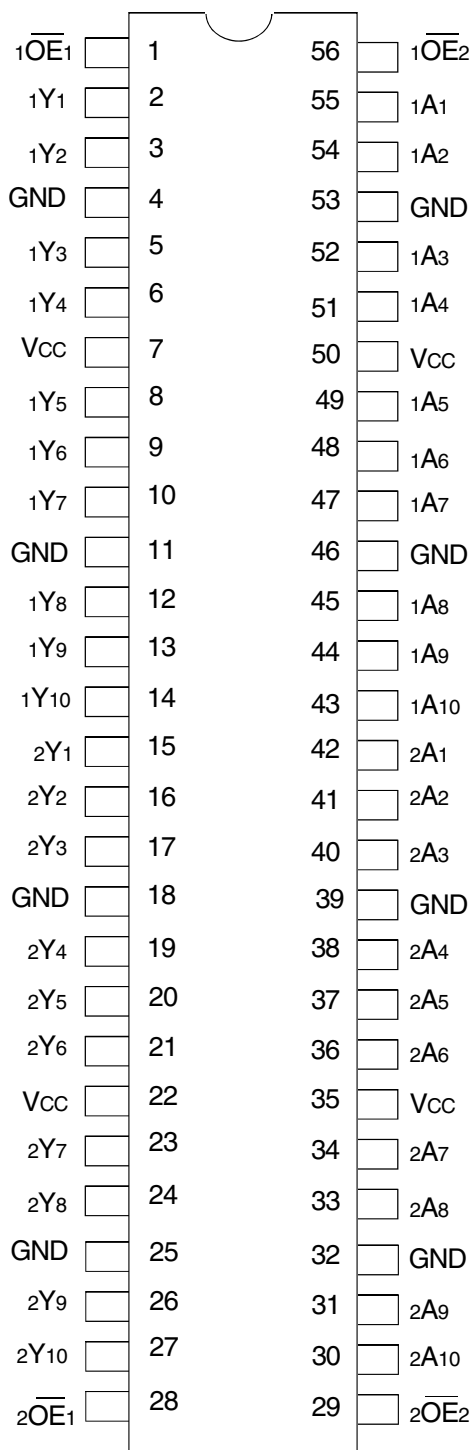
All pins can be driven from either 3.3V or 5V devices. This feature allows the use of the device as a translator in a mixed 3.3V/5V supply system.

The LVC16827A has been designed with a  $\pm 24mA$  output driver. The driver is capable of driving a moderate to heavy load while maintaining speed performance.

FUNCTIONAL BLOCK DIAGRAM



## PIN CONFIGURATION



TSSOP  
TOP VIEW

## ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

Symbol	Description	Max	Unit
VTERM	Terminal Voltage with Respect to GND	-0.5 to +6.5	V
TSTG	Storage Temperature	-65 to +150	°C
IOUT	DC Output Current	-50 to +50	mA
I <sub>IK</sub> I <sub>OK</sub>	Continuous Clamp Current, V <sub>I</sub> < 0 or V <sub>O</sub> < 0	-50	mA
I <sub>CC</sub> I <sub>SS</sub>	Continuous Current through each V <sub>CC</sub> or GND	±100	mA

NOTE:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

## CAPACITANCE (T<sub>A</sub> = +25°C, F = 1.0MHz)

Symbol	Parameter <sup>(1)</sup>	Conditions	Typ.	Max.	Unit
C <sub>IN</sub>	Input Capacitance	V <sub>IN</sub> = 0V	4.5	6	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>OUT</sub> = 0V	6.5	8	pF
C <sub>I/O</sub>	I/O Port Capacitance	V <sub>IN</sub> = 0V	6.5	8	pF

NOTE:

- As applicable to the device type.

## PIN DESCRIPTION

Pin Names	Description
x $\overline{OE}$ x	Output Enable Inputs (Active LOW)
xAx	Data Inputs
xYx	3-State Outputs

## FUNCTION TABLE<sup>(1)</sup>

Inputs			Outputs
x $\overline{OE}$ 1	x $\overline{OE}$ 2	xAx	xYx
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

NOTE:

- H = HIGH Voltage Level  
L = LOW Voltage Level  
X = Don't Care  
Z = High Impedance

## DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Operating Condition:  $T_A = -40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$

Symbol	Parameter	Test Conditions		Min.	Typ. <sup>(1)</sup>	Max.	Unit
V <sub>IH</sub>	Input HIGH Voltage Level	V <sub>CC</sub> = 2.3V to 2.7V		1.7	—	—	V
		V <sub>CC</sub> = 2.7V to 3.6V		2	—	—	
V <sub>IL</sub>	Input LOW Voltage Level	V <sub>CC</sub> = 2.3V to 2.7V		—	—	0.7	V
		V <sub>CC</sub> = 2.7V to 3.6V		—	—	0.8	
I <sub>IH</sub> I <sub>IL</sub>	Input Leakage Current	V <sub>CC</sub> = 3.6V	V <sub>I</sub> = 0 to 5.5V	—	—	±5	μA
I <sub>OZH</sub> I <sub>OZL</sub>	High Impedance Output Current (3-State Output pins)	V <sub>CC</sub> = 3.6V	V <sub>O</sub> = 0 to 5.5V	—	—	±10	μA
I <sub>OFF</sub>	Input/Output Power Off Leakage	V <sub>CC</sub> = 0V, V <sub>IN</sub> or V <sub>O</sub> ≤ 5.5V		—	—	±50	μA
V <sub>IK</sub>	Clamp Diode Voltage	V <sub>CC</sub> = 2.3V, I <sub>IN</sub> = -18mA		—	-0.7	-1.2	V
V <sub>H</sub>	Input Hysteresis	V <sub>CC</sub> = 3.3V		—	100	—	mV
I <sub>CC1</sub> I <sub>CC2</sub> I <sub>CC3</sub>	Quiescent Power Supply Current	V <sub>CC</sub> = 3.6V	V <sub>IN</sub> = GND or V <sub>CC</sub>	—	—	10	μA
			3.6 ≤ V <sub>IN</sub> ≤ 5.5V <sup>(2)</sup>	—	—	10	
ΔI <sub>CC</sub>	Quiescent Power Supply Current Variation	One input at V <sub>CC</sub> - 0.6V, other inputs at V <sub>CC</sub> or GND		—	—	500	μA

NOTES:

1. Typical values are at V<sub>CC</sub> = 3.3V, +25°C ambient.
2. This applies in the disabled state only.

## OUTPUT DRIVE CHARACTERISTICS

Symbol	Parameter	Test Conditions <sup>(1)</sup>		Min.	Max.	Unit
V <sub>OH</sub>	Output HIGH Voltage	V <sub>CC</sub> = 2.3V to 3.6V	I <sub>OH</sub> = -0.1mA	V <sub>CC</sub> -0.2	—	V
		V <sub>CC</sub> = 2.3V	I <sub>OH</sub> = -6mA	2	—	
		V <sub>CC</sub> = 2.3V	I <sub>OH</sub> = -12mA	1.7	—	
		V <sub>CC</sub> = 2.7V		2.2	—	
		V <sub>CC</sub> = 3V		2.4	—	
		V <sub>CC</sub> = 3V		I <sub>OH</sub> = -24mA	2.2	
V <sub>OL</sub>	Output LOW Voltage	V <sub>CC</sub> = 2.3V to 3.6V	I <sub>OL</sub> = 0.1mA	—	0.2	V
		V <sub>CC</sub> = 2.3V	I <sub>OL</sub> = 6mA	—	0.4	
			I <sub>OL</sub> = 12mA	—	0.7	
		V <sub>CC</sub> = 2.7V	I <sub>OL</sub> = 12mA	—	0.4	
		V <sub>CC</sub> = 3V	I <sub>OL</sub> = 24mA	—	0.55	

NOTE:

1. V<sub>IH</sub> and V<sub>IL</sub> must be within the min. or max. range shown in the DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE table for the appropriate V<sub>CC</sub> range. T<sub>A</sub> = -40°C to +85°C.

OPERATING CHARACTERISTICS,  $V_{CC} = 3.3V \pm 0.3V$ ,  $T_A = 25^\circ C$

Symbol	Parameter	Test Conditions	Typical	Unit
CPD	Power Dissipation Capacitance per Buffer/Driver Outputs enabled	$C_L = 0pF$ , $f = 10MHz$		pF
CPD	Power Dissipation Capacitance per Buffer/Driver Outputs disabled			

SWITCHING CHARACTERISTICS<sup>(1)</sup>

Symbol	Parameter	$V_{CC} = 2.7V$		$V_{CC} = 3.3V \pm 0.3V$		Unit
		Min.	Max.	Min.	Max.	
$t_{PLH}$ $t_{PHL}$	Propagation Delay xAx to xYx	1.5	4.7	1.5	4.1	ns
$t_{PZH}$ $t_{PZL}$	Output Enable Time $\overline{xOEx}$ to xYx	1.5	6.5	1.5	5.8	ns
$t_{PHZ}$ $t_{PLZ}$	Output Disable Time $\overline{xOEx}$ to xYx	1.5	6.4	1.5	5.7	ns
$t_{SK(o)}$	Output Skew <sup>(2)</sup>	—	—	—	500	ps

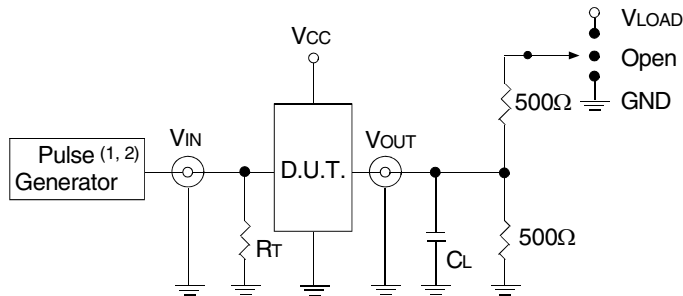
NOTES:

1. See TEST CIRCUITS AND WAVEFORMS.  $T_A = -40^\circ C$  to  $+85^\circ C$ .
2. Skew between any two outputs of the same package and switching in the same direction.

## TEST CIRCUITS AND WAVEFORMS

### TEST CONDITIONS

Symbol	V <sub>CC</sub> <sup>(1)</sup> =3.3V±0.3V	V <sub>CC</sub> <sup>(1)</sup> =2.7V	V <sub>CC</sub> <sup>(2)</sup> =2.5V±0.2V	Unit
V <sub>LOAD</sub>	6	6	2 x V <sub>CC</sub>	V
V <sub>IH</sub>	2.7	2.7	V <sub>CC</sub>	V
V <sub>T</sub>	1.5	1.5	V <sub>CC</sub> / 2	V
V <sub>LZ</sub>	300	300	150	mV
V <sub>HZ</sub>	300	300	150	mV
C <sub>L</sub>	50	50	30	pF



Test Circuit for All Outputs

#### DEFINITIONS:

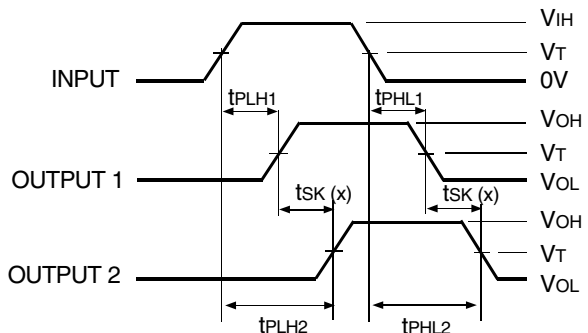
C<sub>L</sub> = Load capacitance: includes jig and probe capacitance.  
R<sub>T</sub> = Termination resistance: should be equal to Z<sub>OUT</sub> of the Pulse Generator.

#### NOTES:

1. Pulse Generator for All Pulses: Rate ≤ 10MHz; t<sub>F</sub> ≤ 2.5ns; t<sub>R</sub> ≤ 2.5ns.
2. Pulse Generator for All Pulses: Rate ≤ 10MHz; t<sub>F</sub> ≤ 2ns; t<sub>R</sub> ≤ 2ns.

### SWITCH POSITION

Test	Switch
Open Drain Disable Low Enable Low	V <sub>LOAD</sub>
Disable High Enable High	GND
All Other Tests	Open

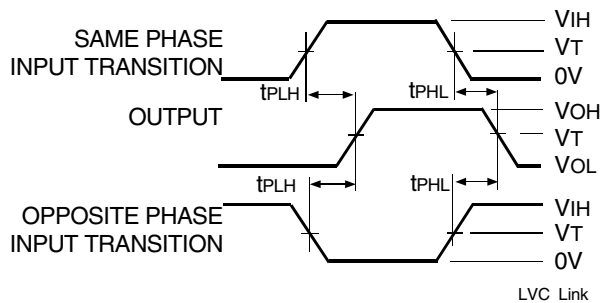


$$tsk(x) = |t_{PLH2} - t_{PLH1}| \text{ or } |t_{PHL2} - t_{PHL1}|$$

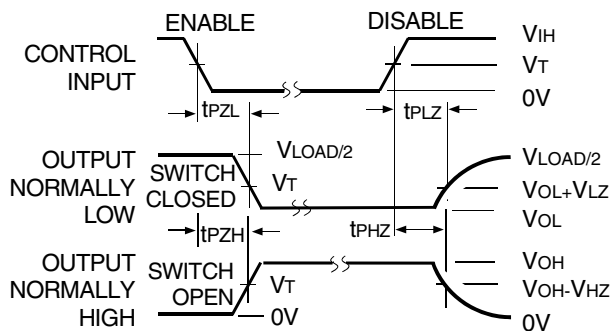
Output Skew - tsk(x)

#### NOTES:

1. For tsk(o) OUTPUT1 and OUTPUT2 are any two outputs.
2. For tsk(b) OUTPUT1 and OUTPUT2 are in the same bank.



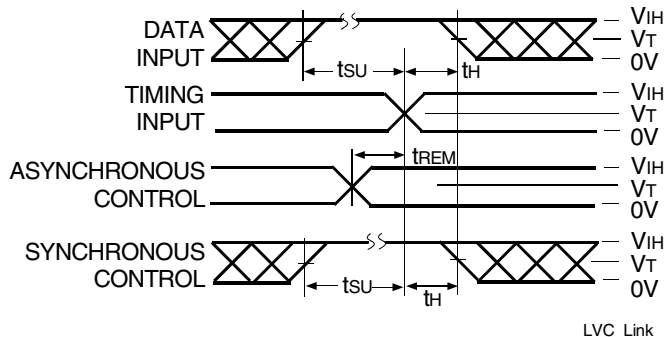
Propagation Delay



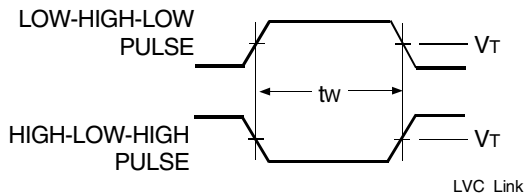
Enable and Disable Times

#### NOTE:

1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.

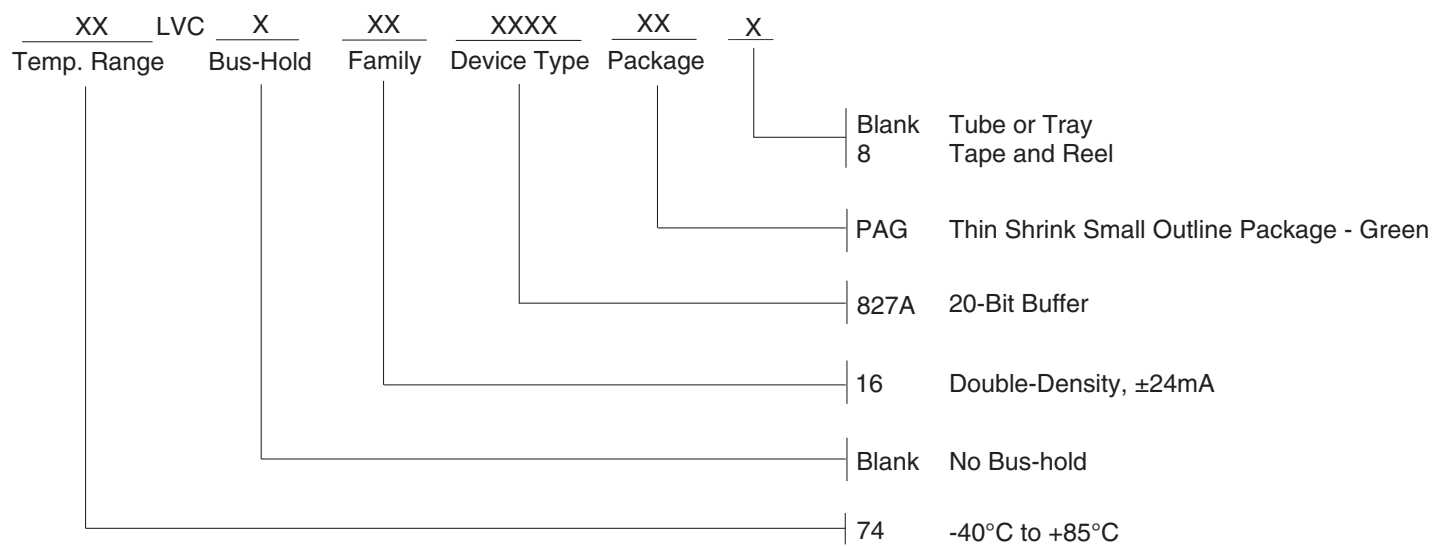


Set-up, Hold, and Release Times



Pulse Width

## ORDERING INFORMATION



## DATASHEET DOCUMENT HISTORY

08/20/2015 Pg. 6 Updated the ordering information by removing non RoHS parts and adding Tape and Reel information.

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